

Process for correcting the thickness of a piezoelectric layer

Abstract

The invention relates to a process for correcting the thickness of a piezoelectric layer (3) arranged on a piezoelectric-on-insulator substrate, comprising the following steps:

- measuring the thickness of at least one intermediate layer (2) located between the piezoelectric layer (3) and a carrier substrate (1),
- measuring the thickness of the piezoelectric layer (3),
- based on said measurements of the thickness of the at least one intermediate layer (2) and of the piezoelectric layer (3) and on a numerical model of at least one property of the piezoelectric layer (3) as a function of a plurality of pairs of thicknesses of the piezoelectric layer (3) and of said at least one intermediate layer (2), computing a thickness correction for the piezoelectric layer (3) with a view to obtaining a target value for each property, and applying the thickness correction to the piezoelectric layer (3) using a milling process in a topographically discriminating manner.

Figure for the Abstract: Fig 2E